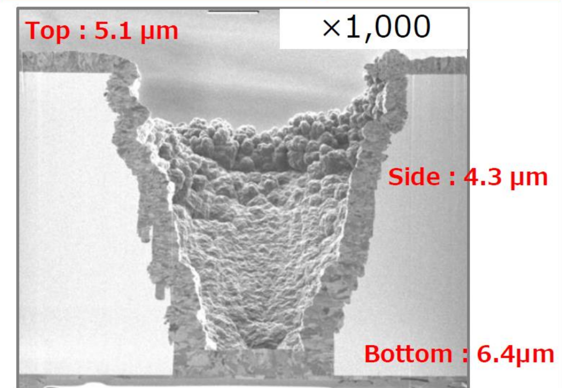
SKY LANE
Plating Using the Full Auto Equipment

This is the latest semiconductor equipment capable of composite plating of copper plating, Ni plating, and Au plating.

The process costs for copper and nickel anodes are significantly reduced, and the process costs for gold can also be significantly reduced.

Our proprietary All round contact
to wafer Excellent current distribution,
It enables high plating speeds and also provides excellent uniformity of plating

Thickness uniformity in a wafer via



High-uniformity gold plating from the SKY LANE

Applications

- Wafer level packaging
- Flip-chip interconnects
- Solder bumping (with nickel & solder plating)
- C4 bump
- Thermo-compression bonding
- And more…

The single-wafer processing Solstice Platform is available with 8, 4, 3 or 2 chambers in customizable configurations, depending on the applications you require.

Features

- Face down flow Control chamber
- All round contact ring
- Auto dosing solution system
- Double（Dry and wet）hand Scara Robot
- 8inch× 8 Chamber system
- 2 Spin Rinse dryer

Technical Spec	
Wafer Sizes	150-200mm
Wafer type	Notch / Flat
Wafer Thickness	200µm to >6mm
Wafer Materials	Silicon GaAs GaN on Si, GaN on Sapphire Sapphire Transparent substrates and more
Maximum quantity of chamber	8 chamber
Equipment size 8C	W2300×L4200×H2200（mm）
Control tower size	W800×L800×H2000(mm)
Power supply	220V 3P 125A
Plating tank capacity	70ℓ
Temp control	±2℃
Rectifier maximum current value	20A
Flow Rate	25 lpm
Plating Rate	>3µm/minute, up to 6.5µm/minute(※about）
Within-Wafer Uniformity	<5% (range 2*mean)
Wafer-to-Wafer Uniformity	<5% (mean-to-mean)
CD Reduction	0.2Å on 20Å seed deplate
Coplanarity	<5%
Communication method	Ethernet and CC Link

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